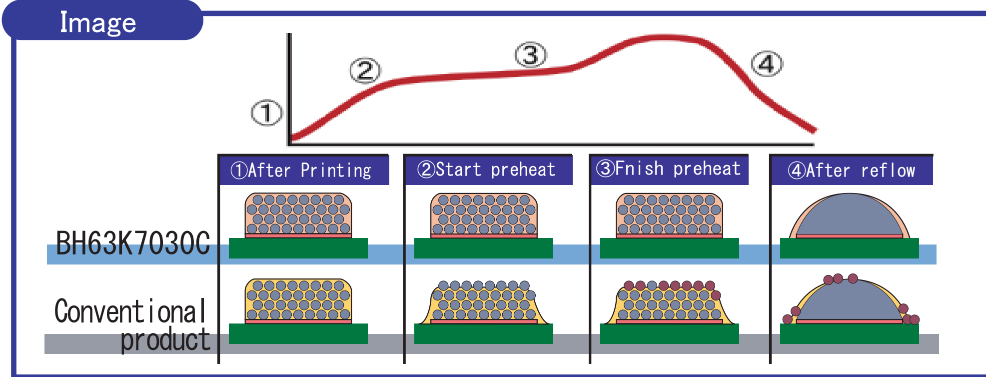
SOLDIM BH63K7030C

Heat-resistant realization in high temperature

In conventional product, flux contained in solder paste is flowed by reflow heating. And powder which aren't coverd by flux is oxidized. It means not good wettability.
However, We have adjusted viscosity of flux in heating and improved heat-resistant realization. It means flux isn't flowed and solder powder isn't oxidized. And This BH63K7030C has good wettability.



Wetability test

Flux contained in BH63K7030C has good thermo-stability. In preheat and reflow, flux isn't flowed. Solder powder isn't oxidized and wettability is good.

	Preheat 150℃	Preheat 170℃
0603 Chip		
0.5mm Pitch QFP		

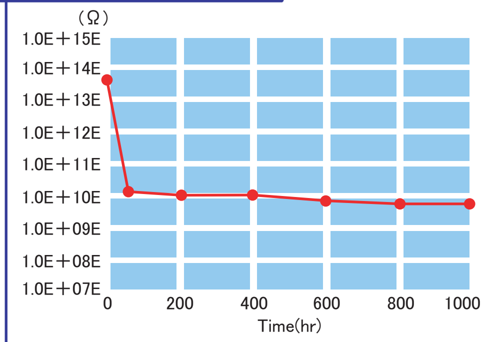
Void test

BH63K7030C has good wettability and less voids caused by de-wetting.

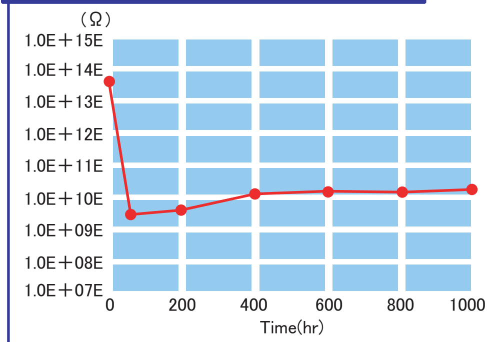
BH63K7030C	Conventional product

Reliability test

Flux residue of BH63K7030C after reflow has good electric reliability.



Test condition:85℃90%RH×1000hr

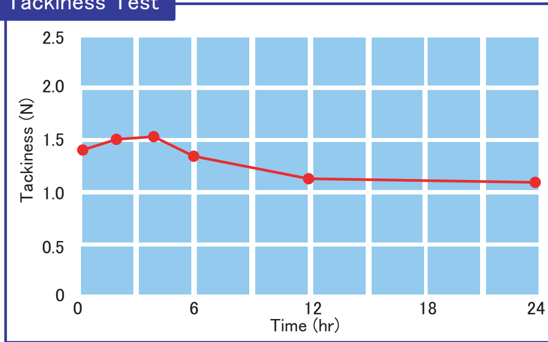


Test condition:85℃90%RH×1000hr(DV50V)

※No Migration

Tackiness Test

Tackiness of BH63K7030C is stable over long time.



Test condition:25℃

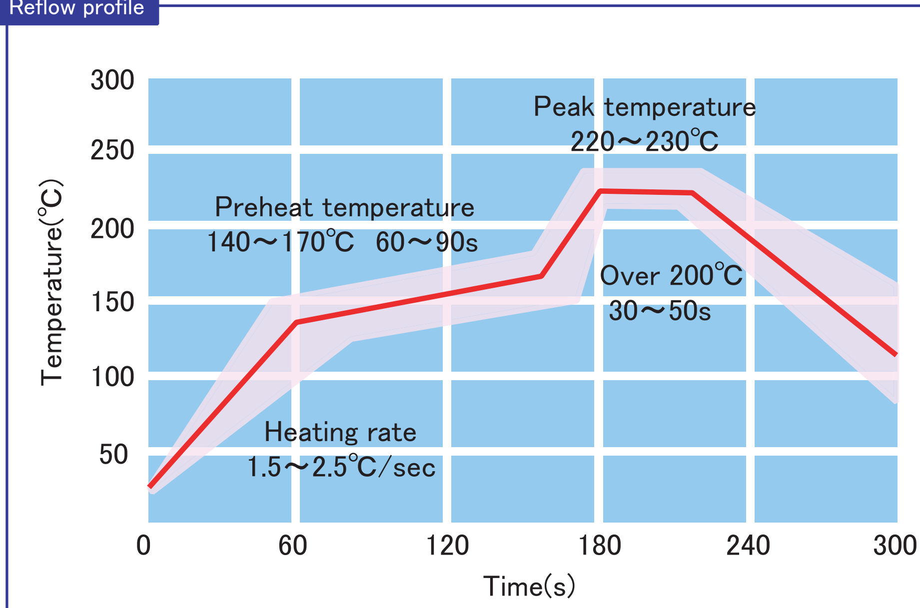
Charactaristic Data

Charactaristic data of BH63K7030C is shown below.

Product name	BH63K7030C
Alloy composition(%)	Sn:63, Pb:Blance
Melting point(℃)	183
Powder particle size(μm)	38～25
Halide content(%)	0.12※1
Flux contents(%)	9.5
Spreading ratio(%)	93
Copper plate corrosion test	Pass
Viscosity(Pa･s)	210
Tackiness test	>24Hr
Strage stability	6 months(Under10℃)

※ Above values are typical value.
※1 This solder paste contain non-ionic halide activator.

Recommendable temperature profile



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